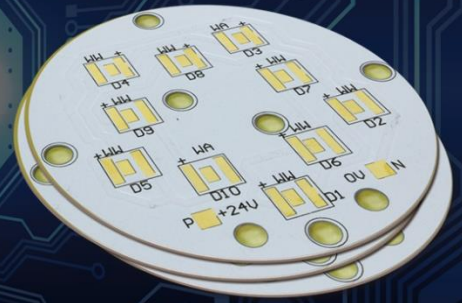


# Thermally Set Pad



## Description

Thermally Set Pad (TSPF) is a thermal interface material that combines the advantages of low thermal resistance, electrical isolation, and thermally set properties. Based on the fluorine resin and specific ceramic filler, this product can be used as the interface material used in the electric component manufacturing of home appliances, electric motors, LED bulbs, power electronics, printed circuit boards, heat sinks and more. Compared with tradition thermal interface materials, TSPF provides more design freedoms, particularly in applications that require thinly shaped structures, high reliability, broad operating temperature ranges, and high thermal conductivity.

## Applications

- Home Appliances
- Electronic Devices
- Electric Motors/Automotive
- High Brightness LED Module



## Features

- Excellent Thermal Conductivity
- Easy to Process
- Flexible Thickness – low thermal resistivity
- Broad Operating Temperature
- RoHS compliant
- Halogen free & lead-free process



**Thermal Management Product**

Items	Unit	TSPF
Thermal Conductivity	W/mK	8
Color	-	Gray to White
Thickness	Um	200
Hardness Before Curing	Shore A	77
Hardness After Curing	Shore A	90
Water Absorption	%	<0.5
Peel Strength w/ Al plate	Kg/cm	>4
Tensile Elongation	%	70
Tensile Strength	MPa	1.3
Out-Gassing Total Mass Loss wt	%	0
Continuous Use Temp	°C	-40°C to 250°C

**ELECTRICAL**

Breakdown Voltage	KV/ mm	> 30
Dielectric Constant (1000 Hz)		7.3
Volume Resistance	ohm	$3.38 \times 10^{12}$
Flammability	-	V-0

**THERMAL PERFORMANCE**

Thickness	Um	100	160	200
Thermal Resistance	°C/W	0.085	0.15	0.21

**Part Number**

TSPF - □ □ -

